

Husch Blackwell LLP
120 South Riverside Plaza, Suite 2200
Chicago, IL 60606
(312) 655-1500 Phone
(312) 655-1501 Fax

TO: Examiner Marianne L. Padgett

PAGES: 4 including cover

FAX NO.: 571-273-1425

FROM: Mark J. Murphy

DATE: May 16, 2011

SERIAL NO.: 10/827,457

OUR FILE NO.: 0553-0408



IF YOU DO NOT RECEIVE ALL PAGES OR ARE HAVING TROUBLE, PLEASE CALL (312) 655-1500
IMMEDIATELY AND ASK FOR LISA HARRIS AT EXT. 226.
THANK YOU.

***** CONFIDENTIALITY NOTE *****

The documents accompanying this facsimile transmission contain information which may be confidential or privileged and exempt from disclosure under applicable law. The information is intended to be for the use of the individual or entity named on this transmission sheet. If you are not the intended recipient, be aware that any disclosure, copying, distribution or use of the contents of this information is without authorization and is prohibited. If you have received this facsimile in error, please notify us by collect telephone immediately so that we can arrange for the retrieval of the original documents at no cost to you.

attachment to interview held May 16, 2011
& entered in scanned file May 17, 2011

Attorney Docket No.: 0553-0408

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Shinji MAEKAWA et al.)
)
Serial No.: 10/827,457)
)
Filed: April 19, 2004)
)
For: Method For Forming Pattern And)
Drop Discharge Apparatus)
)
Examiner: Marianne L. Padgett)
)
Art Unit: 1715)
)
Confirmation No.: 2984)

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

PROPOSED AMENDMENT L

Applicants have the following response to the Office Action of February 16, 2011.

Please amend the above-identified application as follows:

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A pattern forming method comprising steps of:

forming a thin film on a surface;

positioning the surface and ~~[[,]]~~ a first nozzle and a second nozzle, the first and the second nozzles ~~being integrated~~, so that the first nozzle ~~is~~ and the second nozzle are in a region located above a selected portion of the thin film;

irradiating the selected portion of the ~~liquid-repellent~~ thin film with ~~[[a]]~~ plasma ~~[[of a]]~~ gas ~~irradiated~~ originating from the first nozzle to selectively provide affinity for ~~[[the]]~~ a liquid composition to the selected portion, after the step of positioning the ~~integrated~~ first nozzle ~~and the integrated second nozzle~~; and

applying ~~[[a]]~~ the liquid composition to the selected portion by discharging a drop from ~~[[the]]~~ a second nozzle by drop discharging method, after having irradiated the selected portion with ~~[[the]]~~ plasma gas,

forming a pattern by repeating said steps of positioning, irradiating, and applying,

etching the thin film by plasma etching using plasma gas ~~irradiated~~ sprayed by an array of nozzles over an area including the selected portion of the thin film and the pattern, and using the pattern as mask;

wherein a larger quantity of plasma gas is irradiated sprayed over regions where the thin film is exposed than over the pattern ~~varies according to the pattern~~.

The undersigned wishes to discuss this claim and the 112 rejection with the Examiner.

Date:

Respectfully submitted,

Mark J. Murphy
Registration No. 34,225

Husch Blackwell LLP
120 South Riverside Plaza
Chicago, Illinois 60606
(312) 526-1533

Customer No. 24628